What is claimed is:

1. An interconnect stage comprising:
   a. a vertical symmetry plane;
   b. a rotation axis substantially perpendicular to said symmetry plane:
   c. a conductive see-saw structure including:
      i. a substantially planar central portion horizontally extending around an intersection of said symmetry plane and said rotation axis;
      ii. a first peripheral arm laterally extending from said central portion along said symmetry plane and peripherally terminating in a first contact tip, said first arm pointing downwards in a first angle with respect to said planar central portion;
      iii. a second peripheral arm laterally extending from said central portion along said symmetry plane and peripherally terminating in a second contact tip, said second arm extending in opposing position and orientation to said first arm, said second arm pointing upwards in a second angle with respect to said planar central portion;
   d. a dielectric resilient means including:
      i. an interface portion combined with said central portion;

ii. two torsion features laterally extending from opposing ends of said interface portion along said rotation axis; and

wherein said resilient means is configured to be peripherally fixed and configured such that a force induced onto at least one of said first contact tip and said second contact tip results in a rotational displacement of said see-saw structure around said rotation axis, said rotational displacement being opposed by a resiliently torsion deformation of said torsion features.

2. The interconnect stage of claim 1, wherein said see-saw structure is substantially symmetric with respect to said symmetry plane.

3. The interconnect stage of claim 1, wherein said resilient means is substantially symmetric with respect to said symmetry plane.

4. The interconnect stage of claim 1, wherein said see-saw structure is substantially symmetric with respect to said rotation axis.

5. The interconnect stage of claim 1, wherein said resilient means is substantially symmetric with respect to said rotation axis.

6. The interconnect stage of claim 1, wherein said resilient means has a constant thickness.

7. The interconnect stage of claim 1, wherein said see-saw structure has a constant thickness.

8. The interconnect stage of claim 1, wherein said see-saw structure further features a slot propagating from at least one of said first contact tip and said second contact tip along said symmetry plane towards said rotation axis, wherein said slot conductively divides at least partially at least one of said first peripheral arm, said second peripheral arm and said central portion.

9. The interconnect stage of claim 8, wherein said slot propagates between said first contact tip and said second contact tip dividing said see saw structure into at least two conductively separated entities.

10. The interconnect stage of claim 1, wherein said interface portion occupies a fraction of said planar central portion such that a top and a bottom of said central portion are

directly accessible in the vicinity of said peripheral arms.

11. The interconnect stage of claim 1, wherein said interface portion has a first width substantially larger than a second width of said torsion feature such that a delamination origin between said central portion and said interface portion is in a larger distance to said rotation axis than a peak shear point of said dielectric resilient means.

12. The interconnect stage of claim 1, wherein said resilient means further comprises a flex feature extending from at least one of said torsion features in direction substantially parallel to said symmetry plane in an offset to said see-saw structure such that said rotational displacement is additionally opposed by a resilient flexural deformation of said flex feature.

13. The interconnect stage of claim 1, further comprising a stiffening structure combined with said interface portion on the opposite side of said planar center portion.

14. An interconnect assembly comprising:

a. a carrier frame including:

i. a circumferential support frame;

ii. a dielectric carrier grid combined with said circumferential support frame;

b .a number of two dimensionally arrayed interconnect stages, at least one of said interconnect stages comprising:

i. a vertical symmetry plane;

i i a rotation axis substantially perpendicular to said symmetry plane:

iii. a conductive see-saw structure including:

1 .a substantially planar central portion horizontally extending around an intersection of said symmetry plane and said rotation axis;

2 .a first peripheral arm laterally extending from said central portion along said symmetry plane and peripherally terminating in a first contact tip, said first arm pointing downwards in a first angle with respect to said planar central portion;

3 .a second peripheral arm laterally extending from said central portion along said symmetry plane and peripherally terminating in a second contact tip, said second arm extending in opposing position and orientation to said first arm, said second arm pointing upwards in a second angle with respect to said planar central portion;

iv. a dielectric resilient means combined with said carrier grid, said dielectric resilient means including:

1. an interface portion combined with said central portion;

2. two torsion features laterally extending from opposing ends of said interface portion along said rotation axis; and

wherein said resilient means is configured such that a force induced onto at least one of said first contact tip and said second contact tip results in a rotational displacement of said see-saw structure around said rotation axis, said rotational displacement being opposed by a resilient torsion deformation of said torsion features.

15. The interconnect assembly of claim 14, wherein said see-saw structure is substantially symmetric with respect to said symmetry plane.

16. The interconnect assembly of claim 14, wherein said resilient means is substantially symmetric with respect to said symmetry plane.

17. The interconnect assembly of claim 14, wherein said see-saw structure is substantially symmetric with respect to said rotation axis.

18. The interconnect assembly of claim 14, wherein said resilient means is substantially symmetric with respect to said rotation axis.

19. The interconnect assembly of claim 14, wherein said resilient means has a constant thickness.

20. The interconnect assembly of claim 14, wherein said see-saw structure has a constant thickness.

21. The interconnect assembly of claim 14, wherein said see-saw structure further features a slot propagating from at least one of said first contact tip and said second contact tip along said symmetry plane towards said rotation axis, wherein said slot conductively divides at least partially at least one of said first peripheral arm, said second peripheral arm and said central portion.

22. The interconnect assembly of claim 21, wherein said slot propagates between said first contact tip and said second contact tip dividing said see saw structure into at least two conductively separated entities.

23. The interconnect assembly of claim 14, wherein said interface portion occupies a fraction of said planar central portion such that a top and a bottom of said central portion are directly accessible in the vicinity of said peripheral arms.

24. The interconnect assembly of claim 14, wherein said interface portion has a first width substantially larger than a second width of said torsion feature such that a delamination origin between said central portion and said interface portion is in a larger distance to said rotation axis than a peak shear point of said dielectric resilient means.

25. The interconnect assembly of claim 14, wherein said torsion features of each of said number of interconnect stages are fixed at and protruding from x-oriented grid members of said carrier grid.

26. The interconnect assembly of claim 14, wherein said torsion features and said interface feature of each of said number of interconnect stages define y-oriented grid members of said carrier grid.

27. The interconnect assembly of claim 14, wherein said resilient means further comprises a flex feature extending from at

least one of said torsion features in direction substantially parallel to said symmetry plane in an offset to said see-saw structure such that said rotational displacement is additionally opposed by a resilient flexural deformation of said flex feature.

28. The interconnect assembly of claim 27, wherein said flex feature is part of an x-oriented grid member of said carrier grid.

29. The interconnect assembly of claim 27, wherein an x-oriented grid member of said carrier grid is defined by a number of said flex feature of each of said number of interconnect stages.

30. The interconnect assembly of claim 14, further comprising a stiffening structure combined with said interface portion on the opposite side of said planar center portion.

31. The interconnect assembly of claim 14 being part of a test apparatus for repetitively receiving and testing a circuit chip, wherein said first second contact tip of at least one of said number of interconnect stages is contacting a first contact of said test apparatus and wherein said second contact tip of at least one of said number

of interconnect stages is contacting a second contact of said circuit chip.

32. The interconnect assembly of claim 14 fabricated by a method including the steps of:

a. conductively combined planar shaping of a number of said see-saw structure;

b. fabricating said carrier frame;

c. combining said number of said conductively combined and planar shaped see-saw structures with said carrier frame;

d. electro plating said number of conductively combined and planar shaped see-saw structures and consecutively releasing said number of said planar shaped see-saw structures; and

e. 3D forming said number of said released planar shaped see-saw structures.